

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1           **Claim 1 (original):**    An electronic part mounting  
2    apparatus for mounting an electronic part on a substrate,  
3    comprising:  
4           a chamber for cleaning a substrate and an electronic  
5    part by plasma;  
6           a conveying mechanism for conveying said electronic  
7    part and said substrate from said chamber into atmospheric  
8    air;  
9           a mounting mechanism for receiving said electronic  
10   part and said substrate from said conveying mechanism and  
11   for mounting said electronic part on said substrate in a  
12   state that said electronic part and said substrate are  
13   exposed in the atmospheric air.

1           **Claim 2 (original):**    An electronic part mounting  
2    apparatus according to claim 1,  
3           wherein said mounting mechanism includes a part holder  
4    for holding said electronic part, a substrate holder for  
5    holding said substrate, and a moving mechanism for moving  
6    said part holder relative to said substrate holder, and

7           one of said part holder and said substrate holder  
8   includes a heating portion for heating objects to be held  
9   after said electronic part is mounted on said substrate.

1           **Claim 3 (original):**   An electronic part mounting  
2   apparatus according to claim 2, wherein heating operation  
3   of said heating portion is stopped in the middle of  
4   temperature increasing of said objects to be held.

1           **Claim 4 (original):**   An electronic part mounting  
2   apparatus according to claim 2, wherein both said part  
3   holder and said substrate holder include said heating  
4   portions.

1           **Claim 5 (currently amended):**   An electronic part  
2   mounting apparatus according to ~~any of claims~~ claim 1,  
3   further comprising an ultrasonic vibration source for  
4   applying an ultrasonic vibration to said part holder.

**Claims 6-10 (cancelled)**

1           **Claim 11 (new):**   An electronic part mounting apparatus  
2   according to claim 1, further comprising a stage for  
3   placing said electronic part and said substrate thereon in  
4   said chamber.

1           **Claim 12 (new):** An electronic part mounting apparatus  
2   according to claim 1, wherein said substrate and said  
3   electronic part are cleaned in one chamber.